APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention

IMPROVEMENTS IN GROUNDING AND THERMAL DISSIPATION FOR INTEGRATED CIRCUIT PACKAGES

Application Type : regular, utility
Attorney Docket Number : CA920020049

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

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